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March 2013

FDD050N03B

N-Channel PowerTrench® MOSFET 30 V, 90 A, 5.0 m Ω

Features

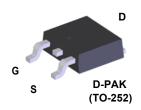
- $R_{DS(on)}$ = 3.7 m Ω (Typ.)@ V_{GS} = 10 V, I_D = 25 A
- · Fast Switching Speed
- Low Gate Charge, Q_G = 33 nC(Typ.)
- High Performance Trench Technology for Extremely Low $R_{\text{DS(on)}}$
- · High Power and Current Handling Capability
- · RoHS Compliant

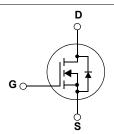
Description

This N-Channel MOSFET is produced using Fairchild Semiconductor[®]'s advance PowerTrench[®] process that has been tailored to minimize the on-state resistance while maintaining superior switching performance.

Applications

• Synchronous Rectification for ATX / Server / Telecom PSU





MOSFET Maximum Ratings $T_C = 25^{\circ}C$ unless otherwise noted

Symbol		Parameter			Unit
V _{DSS}	Drain to Source Voltage			30	V
V _{GSS}	Gate to Source Voltage	Gate to Source Voltage			V
		- Continuous (T _C = 25°C, Silico	on Limited)	90*	
I _D	Drain Current	- Continuous (T _C = 100°C, Silic	con Limited)	63*	Α
		- Continuous (T _C = 25°C, Pack	age Limited)	50	
I _{DM}	Drain Current	- Pulsed	(Note 1)	360	Α
E _{AS}	Single Pulsed Avalanche Energy (Note 2)			72	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)			2	V/ns
n	Dawer Dissipation	(T _C = 25°C)		65	W
P _D Power Dissipation		- Derate above 25°C		0.43	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range			-55 to +175	°C
T _L	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds			300	°C

*Calculated continuous current based on maximum allowable junction temperature. Package limitation current is 50A.

Thermal Characteristics

Symbol	Parameter	FDD050N03B	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	2.3	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max. (Note 5)	40	C/VV

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDD050N03B	FDD050N03B	D-PAK	330mm	16mm	2500

Electrical Characteristics $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charact	teristics					
BV_{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A$, $V_{GS} = 0V$, $T_C = 25^{\circ}C$	30	-	-	V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I _D = 250μA, Referenced to 25°C	-	13	-	mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 24V, V _{GS} = 0V	-	-	1	μА
I _{GSS}	Gate to Body Leakage Current	$V_{GS} = \pm 16V, V_{DS} = 0V$	-	-	±100	nA

On Characteristics

V _{GS(th)}	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	1.25	2.0	3.0	V
Р	R _{DS(on)} Static Drain to Source On Resistance	$V_{GS} = 10V, I_D = 25A$	-	3.7	5.0	mΩ
NDS(on)		V _{GS} = 4.5V, I _D = 15A	-	5.2	8.1	11122
9 _{FS}	Forward Transconductance	V _{DS} = 5V, I _D = 50A	-	169	-	S

Dynamic Characteristics

-							
C _{iss}	Input Capacitance	45)/)/ 0)/		-	2160	2875	pF
Coss	Output Capacitance	V _{DS} = 15V, V _{GS} = 0V f = 1MHz		-	805	1070	pF
C _{rss}	Reverse Transfer Capacitance			-	85	130	pF
Q _{g(tot)}	Total Gate Charge at 10V	V _{DD} = 15V, I _D = 50A		-	33	43	nC
Q _{gs}	Gate to Source Gate Charge	V _{GS} = 10V		-	7.8	-	nC
Q _{gs2}	Gate Charge Threshold to Plateau			-	3.8	-	nC
Q_{gd}	Gate to Drain "Miller" Charge		(Note 4)	-	4.6	-	nC

Switching Characteristics

t _{d(on)}	Turn-On Delay Time	V _{DD} = 15V, I _D = 50A	-	14.5	39	ns
t _r	Turn-On Rise Time	$V_{GS} = 10V, R_{GEN} = 4.7\Omega$	-	4.5	18	ns
t _{d(off)}	Turn-Off Delay Time		-	30	70	ns
t _f	Turn-Off Fall Time	(Note	4) _	4.5	19	ns

Drain-Source Diode Characteristics

I_S	Maximum Continuous Drain to Source Diode Forward Current		-	-	90*	Α
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	360	Α
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS} = 0V, I_{SD} = 50A$	-	-	1.3	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0V, I _{SD} = 50A	-	33	-	ns
Q _{rr}	Reverse Recovery Charge	$dI_F/dt = 100A/\mu s$	-	19	-	nC

Notes:

- Repetitive Rating: Pulse width limited by maximum junction temperature
- 2. L = 1mH, I_{AS} = 12A, V_{DD} = 27V, R_G = 25 Ω , Starting T_J = 25 $^{\circ}$ C
- 3. I_{SD} \leq 50A, di/dt \leq 200A/µs, V_{DD} \leq BV_DSS, Starting T_J = 25°C
- 4. Essentially Independent of Operating Temperature Typical Characteristics
- 5. When mounted on a 1 in² pad of 2 oz copper

Typical Performance Characteristics

Figure 1. On-Region Characteristics

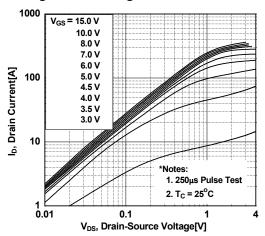


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

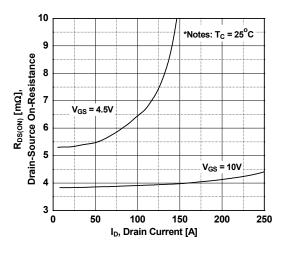


Figure 5. Capacitance Characteristics

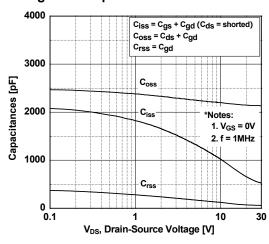


Figure 2. Transfer Characteristics

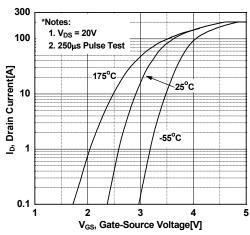


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

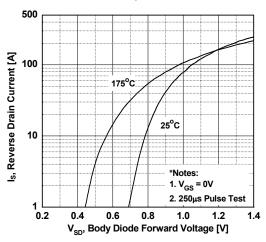
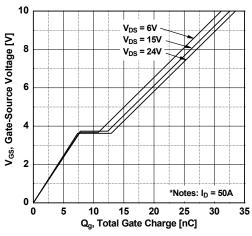


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

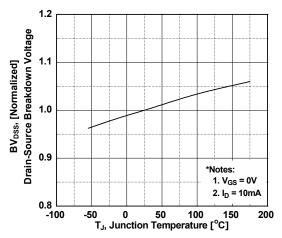


Figure 9. Maximum Safe Operating Area

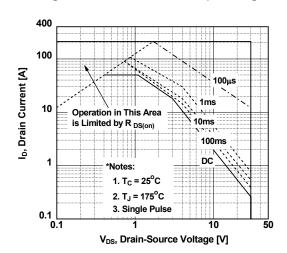


Figure 8. On-Resistance Variation vs. Temperature

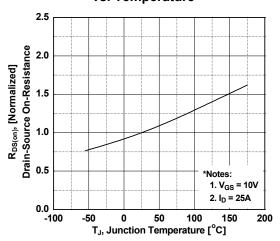


Figure 10. Maximum Drain Current vs. Case Temperature

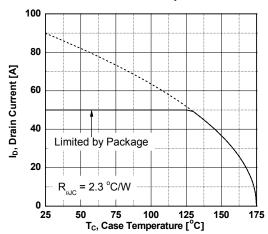
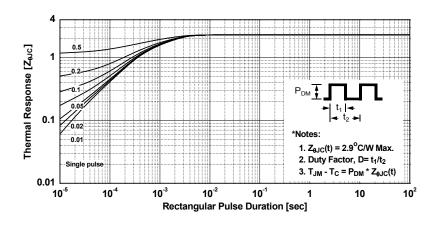
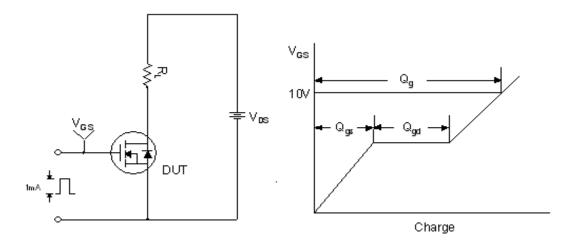


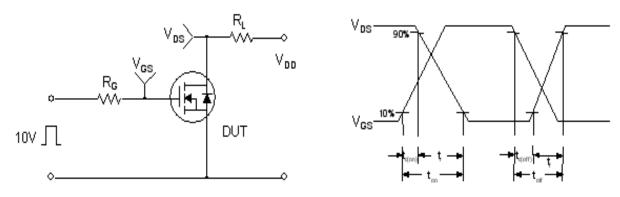
Figure 11. Transient Thermal Response Curve



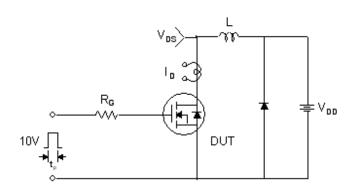
Gate Charge Test Circuit & Waveform

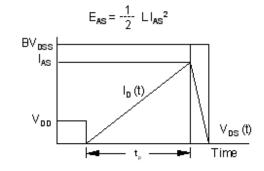


Resistive Switching Test Circuit & Waveforms

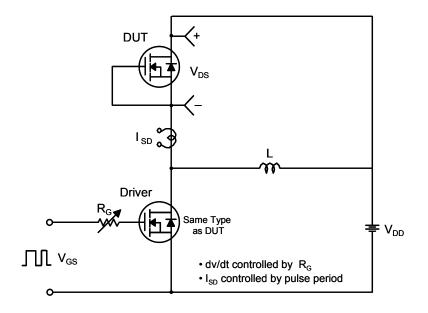


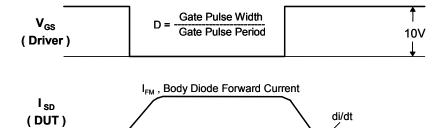
Unclamped Inductive Switching Test Circuit & Waveforms





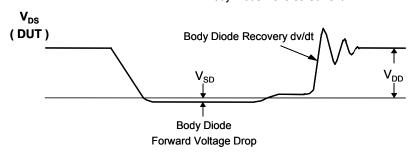
Peak Diode Recovery dv/dt Test Circuit & Waveforms





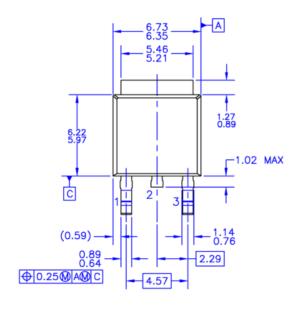
Body Diode Reverse Current

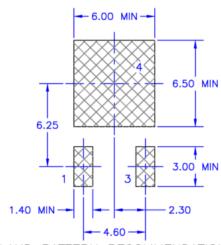
 I_{RM}

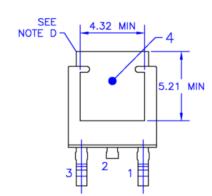


Mechanical Dimensions

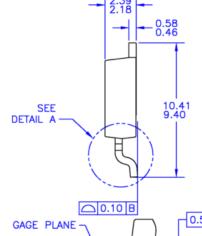
D-PAK











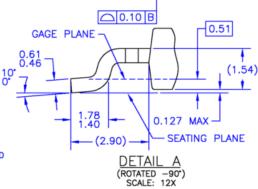
- NOTES: UNLESS OTHERWISE SPECIFIED

 A) THIS PACKAGE CONFORMS TO JEDEC, TO-252, ISSUE C, VARIATION AA.

 B) ALL DIMENSIONS ARE IN MILLIMETERS.

 - c)

 - DIMENSIONING AND TOLERANCING PER
 ASME Y14.5M-1994.
 HEAT SINK TOP EDGE COULD BE IN CHAMFERED
 CORNERS OR EDGE PROTRUSION.
 PRESENCE OF TRIMMED CENTER LEAD D)
 - E)
 - F)
 - PRESENCE OF TRIMMED CENTER LEAD
 IS OPTIONAL.
 DIMENSIONS ARE EXCLUSSIVE OF BURSS,
 MOLD FLASH AND TIE BAR EXTRUSIONS.
 LAND PATTERN RECOMENDATION IS BASED ON IPC7351A STD
 T0220P1003X238-3N.
 DRAWING NUMBER AND REVISION: MKT-T0252A03REV8



Dimensions in Millimeters





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Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
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